used to covey camera data from camera **102** to storage and processing circuitry in device **10**. The upper surface of thin-film transistor layer **76** contains an array of thin-film transistors and associated conductive traces. As shown in the cross-sectional view of FIG. **8**, the lower surface of thin-film transistor layer **76** may be provided with traces **104**. Flex circuit cable **106** may have contact pads that are electrically connected to camera **102** at end **108** and contact pads that are electrically connected to traces **104** at end **110**. Using this type of arrangement, camera data can be conveyed using traces **104**. This may help reduce or eliminate the need for additional cables in device **10**.

[0061] Camera **102** is merely an example of an electrical component for which signals may be routed through underside traces on thin-film transistor substrate **76**. In general, any electrical component that produces or receives electrical signals in device **10** can be electrically connected to traces **104**. The use of traces **104** on layer **76** can reduce the number of cables used to route signals between these electrical components and processing circuitry in device **10** (i.e., circuits on a main logic board and other storage and processing circuitry in device **10**).

[0062] As shown by dashed line **112**, an antenna may be formed from some of the traces **104** on layer **76**. Antenna **112** may be, for example, an antenna for a local wireless network or a cellular telephone.

[0063] Traces **104** may be formed from any suitable conductor. In typical configurations for display module **82**, backlighting is provided by structures **80**. It is therefore typically desirable to form traces **104** from transparent conductive materials such as indium-tin oxide. This is, however, merely one illustrative material that may be used for traces **104**. In general, any suitable conductor may be used. Moreover, it is not necessary to form traces **104** on the underside of thin-film transistor substrate layer **76**. Traces **104** may be formed on other glass layers in module **82**. For example, signal paths for camera signals, antenna signals, or other electrical component signals can be formed from indium-tin oxide patterns on the surface of a cover glass layer, a color filter layer (e.g., layer **70**), a glass layer in structures **80**, or other suitable display module layers.

[0064] As shown in the cross-sectional view of FIG. **9**, ink border **88** may be provided with opening **87** and polarizer **68** may be provided with opening **681**. This allows light to pass to and from the lower layers of display module **82**, without forming holes in thin-film transistor substrate layer **76** and color filter glass layer **70**. Even though no hole is formed in layers **70** and **76** (in the FIG. **9** example), light for electronic component **102** may still pass through openings **87** and **681** and may pass through the clear portions of layers **70** and **76** under openings **87** and **681**. Electronic component **102** may be a camera, sensor, or other suitable electronic component. Component **102** may receive light along path **89**. Component **102** may be mounted to the underside of thin-film-transistor layer or, as indicated by dashed line **1020**, may be mounted to the underside of color filter glass layer **70**.

[0065] The perspective view of FIG. **10** shows how an electrical component **102** (e.g., a camera, sensor, antenna, button, or any other suitable component) may be mounted to the upper surface of thin-film transistor substrate layer **76** outside of the active area of display module **82**. The active area of display module **82** may be aligned with color filter **70** or may have an area that is somewhat smaller than the surface area of color filter **70** (i.e., in alignment with the thin-film transistor array on thin-film transistor substrate **76**). As shown in FIG. **10**, conductive traces **94** may also be formed outside of the active area to route signals to and from electrical component **102**.

[0066] In the illustrative arrangement of FIG. **11**, electrical component **102** has been mounted to an upper surface of color filter glass layer **70**. Conductive traces **94** that lie outside of the active area of display module **82** may be used to convey signals to and from electrical component **102**. Conductive traces **94** may be formed on the upper surface of color filter glass layer **70** (e.g., under a polymer coating layer or other protective layer) or may be formed on the lower surface of color filter glass layer **70** or the upper surface layer of thin-film transistor substrate layer **76**. Vias **95** may be formed through color filter glass layer **70** to interconnect component **102** and conductive traces that have been formed lower in the display module stack. Vias may also be formed through other glass layers such as thin-film transistor substrate layer **76** (e.g., to use traces on the lower surface of the thin-film transistor substrate layer to route signals in module **82**).

[0067] FIG. **12** is a cross-sectional side view of a portion of a display module showing how layers of glass such as cover glass layer **360**, color filter glass **70**, and thin-film transistor substrate layer **76** may each have peripheral edge portions **117** that rest on housing wall ledge portion **116** of housing **26**. Module **82** may be provided with a chassis such as metal chassis member **420**. A laterally extending edge portion of member **420** may also rest on ledge **116** below cover glass **360**, color filter **70**, and thin-film transistor substrate **76**. Adhesive **114** may be used to secure these layers to housing **26**.

[0068] FIG. **13** shows an arrangement of the type shown in FIG. **12** in which elastomeric trim **66** (sometimes referred to as a gasket) has extending portion **660**. Extending portion **660** covers portion **26**AA of housing **26** and all of the exposed upper surfaces of housing **26** (i.e., all of surfaces **263**, **265**, and **267**, including the portions of surface **263** that are adjacent to peripheral outer edge **269** of housing **26**). Because all upper surface portions of housing **26** are covered (either with cover glass or trim), the arrangement of FIG. **13** helps improve the cosmetic appearance of device **10** when viewed from direction **661**.

[0069] The foregoing is merely illustrative of the principles of this invention and various modifications can be made by those skilled in the art without departing from the scope and spirit of the invention.

What is claimed is:

1. An electronic device comprising:

a display comprising:

a display layer having an opening, wherein the display layer has a first portion and a second portion and wherein the opening is interposed between the first portion and the second portion;

a cover layer that overlaps the display layer; and

a light-sensing component overlapped by the cover layer, wherein the light-sensing component receives light through the cover layer and is aligned with the opening in the display layer.

2. The electronic device defined in claim **1** further comprising:

a housing having a rear portion and housing walls that extend from the rear portion, wherein the display is mounted in the housing, wherein the housing walls